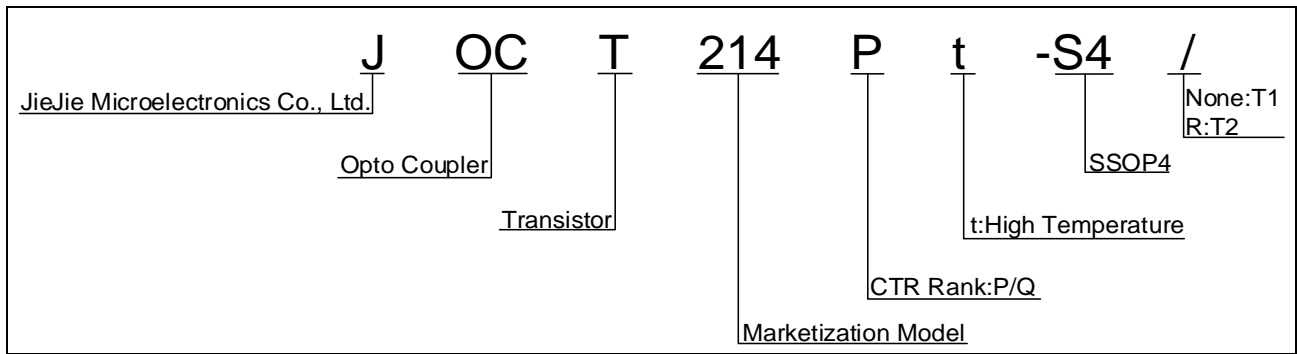


ELECTRICAL CHARACTERISTICS (Temperature=25°C)

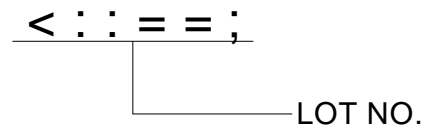
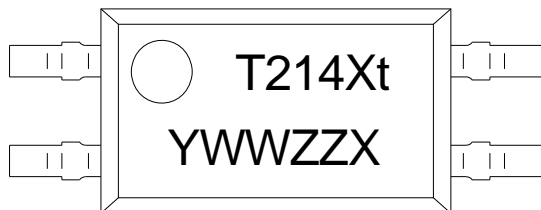
Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F = \pm 10\text{mA}$	-	1.2	1.5	V
	Terminal Capacitance	C_t	$V=0,$ $f=1\text{MHz}$	-	30	250	pF
Output	Collector-Emitter dark current	I_{CEO}	$V_{CE}=20\text{V},$ $I_F=0$	-	-	50	nA
	Collector-Emitter breakdown voltage	BV_{rmin}		0	1		

ORDERING INFORMATION



Packing Quantity	
Option	Quantity
None/R	3000 Units/Reel

MARKING



Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

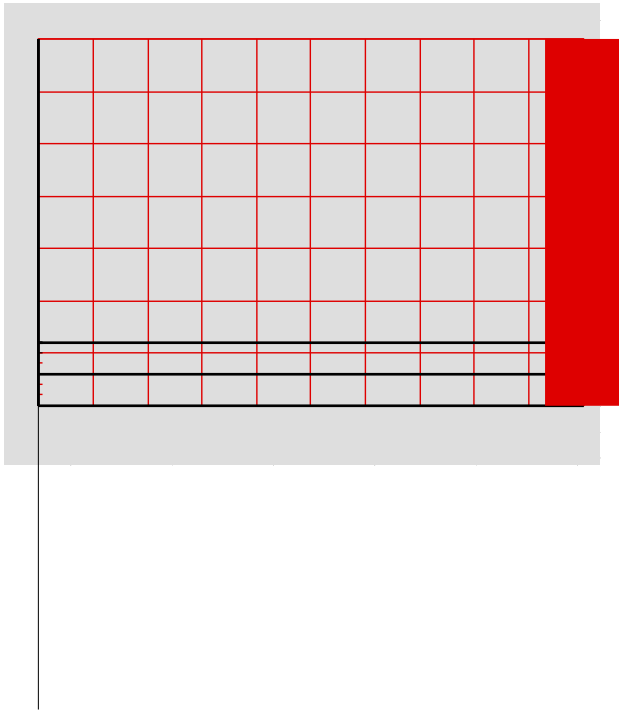


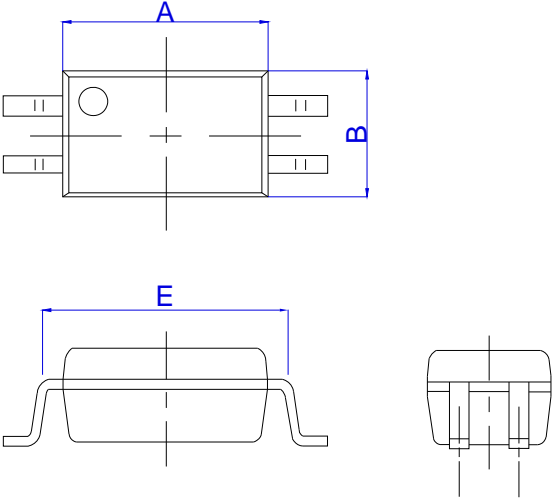
FIG.2: Collector Power Dissipation vs. Ambient Temperature



FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

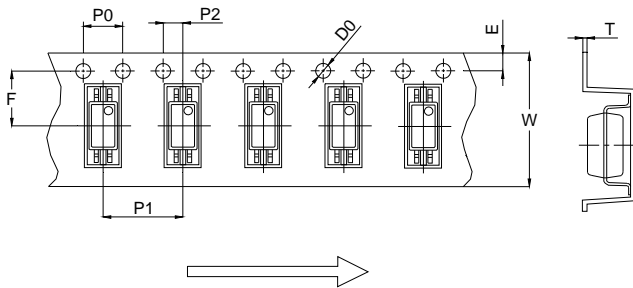
FIG.8: Normalized Collector-emitter Saturation

Package Dimension (Unit: mm)



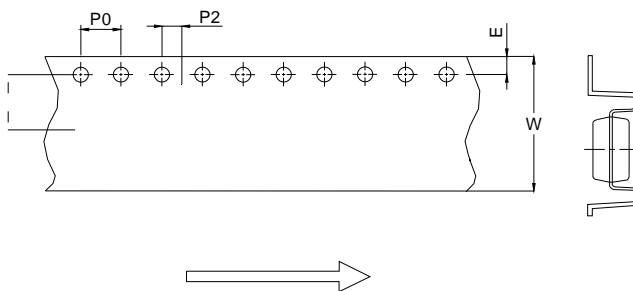
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option None

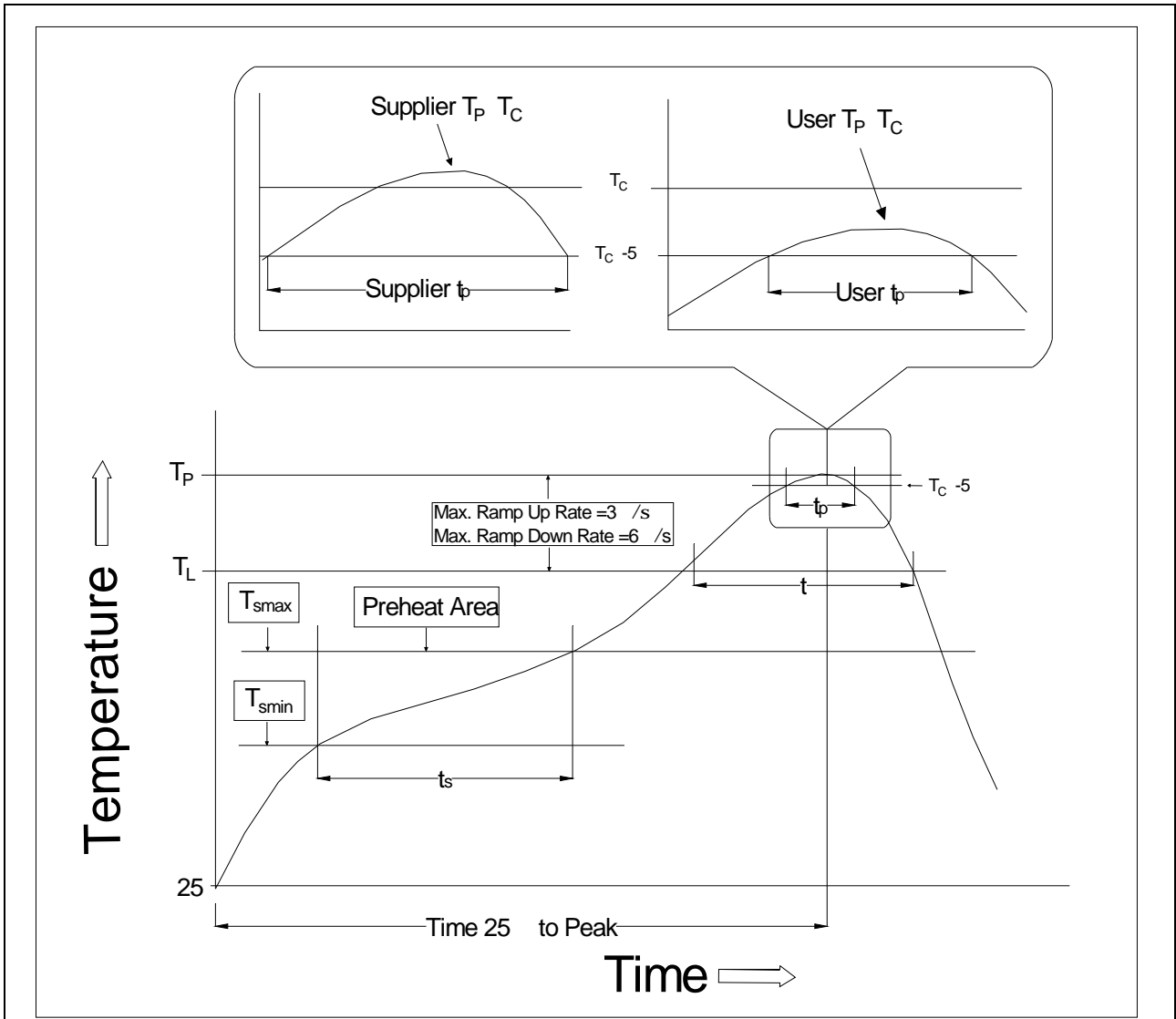


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	5.40	5.50	5.60	0.213	0.217	0.220
T	0.20	0.25	0.30	0.008	0.010	0.012
W	11.90	12.10	12.30	0.469	0.476	0.484

Option R



REFLOW INFORMATION




Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150
Temperature Max. (T _{smax})	150	200
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3 °C/second max.	3 °C/second max.
Liquidus Temperature (T _L)	183	217
Time (t _L) Maintained Above (T _L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (t _P) within 5 °C of 260	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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